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Fig # 1082

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10082472	02/22/2002	438	1015	2827	ZARNEKE

****APPLICANTS:** Yoshida Akito;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO W2K 1077
TITLE : Stacking structure for semiconductor devices using a folded over flexible substrate and method therefor		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-438L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE Amount Due Date Paid		Assistant Examiner	Total Claims Print Claim for O.G.
		Primary Examiner PREPARED FOR ISSUE	DRAWING Sheets Drwg. Figs. Drwg. Print Fig. Application Examiner
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